Standardized Information for Process/Product Change Notification (PCN)

		1. Product Change Notifi	cation [PCN]	basic data			
Customer		Name Customer: Contact Email address:					
1.1 Company	Melexis INSPIRED ENGINEERING	Site submitting the change:		 Melexis leper			
		Affected site(s):	Melexis Supplier				
1.2 PCN No.		MCM-12851					
1.3 Title of PCN		Alternative source IMC process for current sensors products [MLX91206CAH]					
1.4 Product Category		Active Components - Integrated Circuits					
1.5 Issue date		26-Oct-2021					
1.6 Note in ca (optional)	ase of Pre-Initial PCN						
1.7 PCN revision history (optional)		1.8 Issue date of previous 1.9 Delta to previous revision (optional) revision (optional)					

	2. PCN Team
2.1 Contact supplier	

2.1.1 Name	Lisa Vanheerswynghels			
2.1.2 Phone	+32 57 22 62 07			
2.1.3 Email	pcn_mlx@melexis.com			
2.2 Team supplier (optional)				
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)		

	3. Changes				
No.	3.0 Ident	3.1 Category	3.2 Type of change		
#1	SEM-AN-01	ANY	Any change with impact on agreed upon technical contractual agreements		
#2	SEM-DS-02	DATA SHEET	Correction of data sheet or issue of errata		
#3	SEM-PW-08	PROCESS - WAFER PRODUCTION	New / change of passivation or die coating (without bare die)		
#4	SEM-PW-12	PROCESS - WAFER PRODUCTION	Change of specified wafer process sequence (deletion and/or additional process step)		
#5	SEM-PW-13	PROCESS - WAFER PRODUCTION	Move all or parts of production to a different wafer fab site.		
#6	SEM-PA-04	PROCESS - ASSEMBLY	Change of lead frame finishing material / area (internal)		
#7	SEM-PA-07	PROCESS - ASSEMBLY	Die attach material		
#8	SEM-PA-11	PROCESS - ASSEMBLY	Change of mold compound / encapsulation material		

#9	SEM-PA-13	PROCESS - ASSEMBLY	Change of product marking
#10	SEM-PA-17	PROCESS - ASSEMBLY	Change of specified assembly process sequence (deletion and/or additional process step)
#11	SEM-EQ-01	EQUIPMENT	Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product

4. Description of change			
	Old	New	
Description #1	 IMC design: Octagon shape with hole in the middle IMC material: CoFe 	 IMC design: Octagon shape without hole in the middle IMC material: FeNi 	
Description #2	First row marking: 206CAH Third row marking: YYWW	First row marking: 91206CAH Third row marking: YYWWEH	
Description #3	Interface / adhesion layer: Epoxy	Interface / adhesion layer: Polyimide	
Description #4	Annealing: at raw material level	Annealing: after IMC electroplating	
Description #5	IMC Supplier: Axetris (Switzerland)	IMC Supplier: XFAB-Itzehoe (Germany)	
Description #6	Leadframe: C151 (non-roughened)	Leadframe: C151 (Roughned)	
Description #7	Die Attach: 84-1-LMISR4	Die Attach: 8290	
Description #8	Mold Compound: G600C	Mold Compound: G700HA	
Description #9	First row marking: 206CAH Third row marking: YYWW	First row marking: 91206CAH Third row marking: YYWWEH	
Description #10	No chemical deflash waterjet	chemical deflash waterjet	

Description #11	Glueing and etching of metal strips	Electroplating	
4.6 Anticipated impact on form, fit,	 Based on Risk Assessment including AEC-Q100 and ZVEI § 	guidelines	
function, reliability or processability?	 Wide variety of automotive products qualified. Generic of 	lata available, considering automotive grade	
	- Whenever possible, re-use of Melexis qualified Bill-of-Material & Bill-of-Process will be applied		
4.7 Anticipated impact on order code	No impact, current order codes remain valid		
	The product ordering code will not change as the products will not co-exist, the Axetris process is no longer supported in the futu outside of the inventory built up at Melexis		

5. Reason / motivation for change			
5.1 Motivation	Transfer from Axetris to XFAB-Itzehoe as part of the Melexis long term product strategy and driven by End-of-Life at Axetris. Within this required change, Melexis takes the opportunity to further improve the product.		
5.2 Additional explanation (optional)	Part of Melexis long term product strategy		

	6. Marking of parts / traceability of change
6.1 Description	The marking of the parts will be changed as described in detail in the attached presentation.
	Traceability is ensured by lot number and datecode through the Melexis ERP system.

7. Timing / schedule			
7.1 Date of qualification results	February 2022		
7.2 Last order date (optional)			
7.3 Last delivery date (optional)			
7.4 Intended start of delivery	August 2023	Please contact your Customer Relations responsible for detailed information. Note that the start of delivery can shift depending on the moment Melexis receives the customer approval.	

7.5 Qualification samples available?			
	Yes available Samples can be requested through pcn_mlx@melexis.com		
7.6 Customer feedback required until	09-Nov-2021 Please provide your initial feedback through the 'Customer Feedback' sheet as		
		acknowledgement	

8. Qualification / validation					
8.1 Description (e.g. qualification or validation plan/re - Wide variety of automotive products qualified. Generic data available, considering automotive grade - Whenever possible, re-use of Melexis qualified Bill-of-Material & Bill-of-Process will be applied			de		
8.2 Qualification report and qualification results	Will be available at date:	issue date	March 2022	(expected)	

9. Input to customer for risk assessment process								
See attached presentation: BOM&BOP Risk assessment								

10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...)

MCM-12851 ZVEI delta qualification matrix.xlsm BOM & BOP Risk Assessment_Axetris transfer.xlsx DIGI-KEY_Alternative source IMC Process.pdf

11. Affected parts								
11.1 Current	11.2 New (if applicable)							

11.1.1	11.1.2 Supplier Part Name	11.1.3	11.1.4	11.1.5	11.1.6	11.2.2 Supplier	11.2.3	11.2.4 Package	11.2.6
Customer		Supplier	Package	Part	Addl Part	Part Name	Supplier	Name	Additional Part
Part No.		Part No.	Name	Description	Info (opt)		Part No.		Information
		(opt)		(opt)			(opt)		(opt)
NA	MLX91206LDC-CAH-002-TU		SOIC8 GR						
NA	MLX91206LDC-CAH-004-TU		SOIC8 GR						